

**RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
GROUP 2818  
PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q78657

Hien Boon TAN, et al.

Appln. No.: 10/581,395

Group Art Unit: 2818

Confirmation No.: 3868

Examiner: David J GOODWIN

Filed: August 14, 2008

For: CHIP SCALE PACKAGE AND METHOD OF ASSEMBLING THE SAME

**RESPONSE UNDER 37 C.F.R. § 1.116**

**MAIL STOP AF**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated March 31, 2011, please consider the remarks as submitted herewith on the accompanying pages.